



Material Content Data Sheet



Sales Product Name		BTS5215L		Issued		29. August 2013			
MA#		MA001114912							
Package		PG-DSO-12-9		Weight*		367.39 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.733	1.29	1.29	12884	12884	
leadframe	non noble metal	iron	7439-89-6	0.204	0.06		556		
	inorganic material	phosphorus	7723-14-0	0.061	0.02		167		
	non noble metal	copper	7440-50-8	203.829	55.47	55.55	554806	555529	
wire	non noble metal	aluminium	7429-90-5	0.702	0.19	0.19	1910	1910	
encapsulation	organic material	carbon black	1333-86-4	0.300	0.08		817		
	plastics	epoxy resin	-	21.468	5.84		58433		
	inorganic material	silicondioxide	60676-86-0	128.355	34.94	40.86	349372	408622	
leadfinish	non noble metal	tin	7440-31-5	3.310	0.90	0.90	9009	9009	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		4		
	non noble metal	nickel	7440-02-0	0.617	0.17	0.17	1680	1684	
solder	noble metal	silver	7440-22-4	0.095	0.03		259		
	non noble metal	tin	7440-31-5	0.076	0.02		207		
	non noble metal	lead	7439-92-1	3.636	0.99	1.04	9896	10362	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com